## V

### The Memory Wall



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### Improving Memory Performance

EE 357 Unit 13

Memory System Overview

SRAM vs. DRAM

DMA & Endian-ness

- Possibilities for improvement
  - Technology
    - Can we improve our transistor-level design to create faster RAMs
    - Can we integrate memories on the same chip as our processing logic
  - Architectural
    - Can we organize memory in a more efficient manner (this is our focus)



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#### **DRAM & SRAM**

### Memory Technology

- Static RAM (SRAM)
  - Will retain values indefinitely (as long as power is on)
  - Stored bit is actively "remembered" (driven and regenerated by circuitry)
- Dynamic RAM (DRAM)
  - Will lose values if not refreshed periodically
  - Stored bit is passively "remembered" and needs to be regenerated by external circuitry

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## **Memory Array**

- Logical View = 1D array of rows (words)
  - Already this is 2D because each word is 32-bits (i.e. 32 columns)
- Physical View = 2D array of rows and columns
  - Each row may contain 1000's of columns (bits) though we have to access at least 8- (and often 16-, 32-, or 64-) bits at a time



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## 1Mx8 Memory Array Layout

- Start with array of cells that can each store 1-bit
- 1 MB = 8 Mbit = \_\_\_\_ total cells
- This can be broken into a 2D array of cells (\_\_\_\_\_)
- Each row connects to a WL = \_\_\_\_\_ which selects that row
- Each column connects to a BL = \_\_\_\_\_ for read/write data



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## **Row and Column Address**

- For 1MB we need \_ address bits
- 10 upper address bits can select one of the 1024 rows
- Suppose we always want to read/write an 8-bits (byte), then we will group each set of 8-bits into \_\_\_\_\_ byte columns (1024x8 = 8K)
- \_\_\_\_ lower address bits will select the column



## **Periphery Logic**



**8K Bit Lines** 

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## **Memory Technologies**

- Memory technologies share the same layout but differ in their
- Static RAM (SRAM) – Will
  - (as long as power is on)
  - When read, the stored bit driven onto the is bit lines
- Dynamic RAM (DRAM)
  - Will lose values if not periodicallv When read, the stored bit
  - pulls the bit line voltage up or down slightly and needs to be amplified



### ol of Engineering **DRAM Cell** Bit is stored on a BL capacitor and requires only 1 transistor and a capacitor WL Transistor acting as a switch Capacitor

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### **DRAM Cell**

ΒL

- Bit is stored on a • capacitor and requires only 1 transistor
- Write
  - WL=1 connects the capacitor to the BL which is driven to 1 or 0 and charges/discharges capacitor based on the BL value



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## **DRAM Cell**

- Bit is stored on a capacitor and requires only 1 transistor
- Write

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- WL=1 connects the capacitor to the BL which is driven to 1 or 0 and charges/discharges capacitor based on the BL value
- With WL=0 transistor is closed and value stored on the capacitor



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#### ISC Viterbi SC Viterbi nool of Engineering ool of Engineering **DRAM Cell DRAM** Issues Bit is stored on a ٠ capacitor and requires BL BL – Charge is when only 1 transistor capacitor value is read Write Need to WI WL - WL=1 connects the whatever is read back Transistor acting as Transistor acting as capacitor to the BL which to the cap. a switch a switch is driven to 1 or 0 and charges/discharges **Capacitor charge** capacitor based on the BL Capacitor (or lack of charge) - Charge \_\_\_\_\_ value Read 2.5 V - BL is precharged to 2.5 V - Value must be - WL=1 connects the refreshed periodically capacitor to the BL allowing charge on capacitor to change the Sense amp drives voltage the rest of the Sense voltage on the BL way to 5V or 0V Amp. © Mark Redekopp, All rights reserved © Mark Redekopp, All rights reserved

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## SRAM vs. DRAM Summary

•	SRAM	•
	<ul> <li>Faster because</li> </ul>	
	<ul> <li>Faster, simpler</li> </ul>	
	interface due to lack of	
	refresh	

speed/latency is key

- DRAM
- Slower because
- Slower due to refresh
   k of cycles
- Used for \_\_\_\_\_ vhere density is key

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## MAIN MEMORY ORGANIZATION

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## Architectural Block Diagram

- Memory controller interprets system bus transactions into appropriate chip address and control signals
  - System address and data bus sizes do not have to match chip address and data sizes



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### **Memory Block Diagrams**

- SRAM
  - Bidirectional, shared data bus (only 1 chip can drive bus at a time)
  - CS = Chip select (enables the chip...in the likely case that multiple chips connected to bus)
  - WE / OE = Write / Output Enable (write the data or read data to/from the given address)



DRAM

- Bidirectional, shared data bus (only 1 chip can drive bus at a time)
- RAS / CAS = Row / Column address strobe. Address broken into two groups of bits for the row and column in the 2D memory array (This allows address bus to be approx. half as wide as an SRAM's)
- CS/WE/OE = Chip select & Write / Output Enable



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## Synchronous DRAM Timing



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### **DDR SDRAM Timing**

 Double data rate access data every half clock cycle (on both \_\_\_\_\_\_



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# Banking

- Divide memory into "banks" duplicating \_\_\_\_\_\_ and other peripheral logic to create independent
  - memory arrays that can \_\_\_\_\_
  - $-\,$  uses a portion of the address to determine which bank to access



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### **Bank Access Timing**

- Consecutive accesses to different banks can be overlapped and hide the time to access the row and select the column
- Consecutive accesses within a bank (to different rows) exposes the access latency



### **Memory Modules**

- Integrate several chips on a module
  - SIMM (Single In-line Memory Module) = single sided
  - DIMM (Dual In-line Memory Module) = double sided
- 1 side is termed a \_\_\_\_\_
  - SIMM = \_\_\_\_\_
  - DIMM = \_\_\_\_\_
- Example
  - (8) 1Mx8 chips each output 8 bits (1-byte) to form a 64-bit (8-byte) data bus



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#### Address Breakdown

 Assume a 1GB memory system made of 2 ranks of 64Mx8 chips (4 x 16K x 1K x 8) connected to a 64-bit (8-byte) wide data bus



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 Assume a 1GB memory system made of 2 ranks of 64Mx8 chips (4 x 16K x 1K x 8) connected to a 64-bit (8-byte) wide data bus



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#### Address Breakdown

 Assume 2 GB of memory on a single SIMM module with (8) 256MB each (broken into 8 banks and 8K rows)

Unused	Rank	Row	Bank	Col.	Unused

#### **Memory Summary**

- Opportunities for speedup / parallelism
  - Sequential accesses lowers latency (due to bursts of data via FPM, EDO, SDRAM techniques)
  - Ensure accesses map to different banks and ranks to hide latency (parallel decoding and operation)

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## **Programming Considerations**

- For memory configuration given earlier, accesses to the same bank but different row occur on an 32KB boundary
- Now consider a matrix multiply of 8K x 8K integer matrices (i.e. 32KB x 32KB)
- In code below...m2[0][0] @ 0x10010000 while m2[1][0] @ 0x10018000

	Unused	Rank	Row	Bank	Col.	Unused	
	A31,A30	A29	A28A15	A14,A13	A12A3	A2A0	
0x10010000 —	00	0	1 0000 0000 0001 0	00	000000000	000	
ر 0x10018000	00	0	1 0000 0000 0001 1	00	000000000	000	
<pre>int m1[8192][8192], m2[8192][8192], result[8192][81 int i,j,k;  for(i=0; i &lt; 8192; i++){ for(j=0; j &lt; 8192; j++){ result[i][j]=0; for(k=0; k &lt; 8192; k++){ result[i][j] += matrix1[i][k] * matrix2[k][j]; } } }</pre>							
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### **DMA & ENDIAN-NESS**



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## **Direct Memory Access (DMA)**

• Large buffers of data often need to be copied between:

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DMA devices are small

 devices that
 data from a source
 to destination freeing the
 processor to do "real" work



#### Data Transfer w/o DMA

- Without DMA, processor would have to move data using a loop
- Move 16Kwords pointed to by (\$8) to (\$9)
- addi \$18,\$0,16384 AGAIN: lw \$17,0(\$8) sw \$17,0(\$9) addi \$8,\$8,4 \$9,\$9,4 addi addi \$18,\$18,-1 \$18, \$zero, AGAIN bne



- execution time moving data
- Processor wastes valuable

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### Data Transfer w/ DMA

DMA DMA Control Processor sets values in DMA Registers ds control registers CPU Memory Systen us Control & Status (Start, Stop, Interrupt on Completion, etc.) I/O Bridge DMA becomes (controls system bus to generate reads and writes) while processor I/O Device I/O Device is free to execute other code (USB) (Network) Small problem: I/O Bus - Hopefully, data & code needed by the CPU will reside in

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# **DMA Engines**

- Systems usually have \_\_\_\_\_ DMA engines/channels
- Each can be configured to be started/controlled by the processor or by certain
  - Network or other peripherals can \_\_\_\_\_ on their behalf
- Bus arbiter assigns control of the bus
  - Usually winning requestor has control of the bus until it relinguishes it (turns off its request signal)



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#### **Endian-ness**

- Endian-ness refers to the two • alternate methods of ordering the bytes in a larger unit (word, long, etc.)
  - Big-Endian

 \_\_\_\_\_ is put at the starting address - Little-Endian

- - \_\_\_\_\_ is put at the starting address



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#### USC Viterbi USC Viterbi $(\mathbf{V})$ School of Engineering School of Engineering Big-endian vs. Little-endian Big-endian vs. Little-endian Issues arise when transferring data between different systems **Big-endian** ٠ Little-endian ٠ - Byte-wise copy of data from big-endian system to little-endian system - makes sense if you view - makes sense if you view your Major issue in networks (little-endian computer => big-endian computer) your memory as starting at memory as starting at the and even within a single computer (System memory => Peripheral (PCI) bottom-right and addresses the top-left and addresses device) increasing as you go down increasing as you go up **Coldfire is Big-Endian** Little-Endian **BIG-ENDIAN** 0 1 2 3 0 1 2 3 111 1 1 Copy byte 0 to byte 0, 346678 000000 12345678 000000 byte 1 to byte 1, etc. resses esses 000014 000014 000004 000004 é 000010 000010 000008 easing *t* 000008 increasing downwa asina increasing 00000C 00000C 00000C 00000C incr 800000 000008 000010 000010 Addresses i doy 000004 000014 000004 000014 12345678 000000 000000 3 2 1 0 3 2 1 0 1 2 3 4 5 6 3 4 5 6 78 78 34 78 Long @ addr. 0 1 2 1 2 56 Byte 3 Byte 2 Byte 1 Byte 0 Byte 3 Byte 2 Byte 1 Byte 0 Byte 0 Byte 1 Byte 2 Byte 3 Byte 0 Byte 1 Byte 2 Byte 3 © Mark Redekopp, All rights reserved © Mark Redekopp, All rights reserved